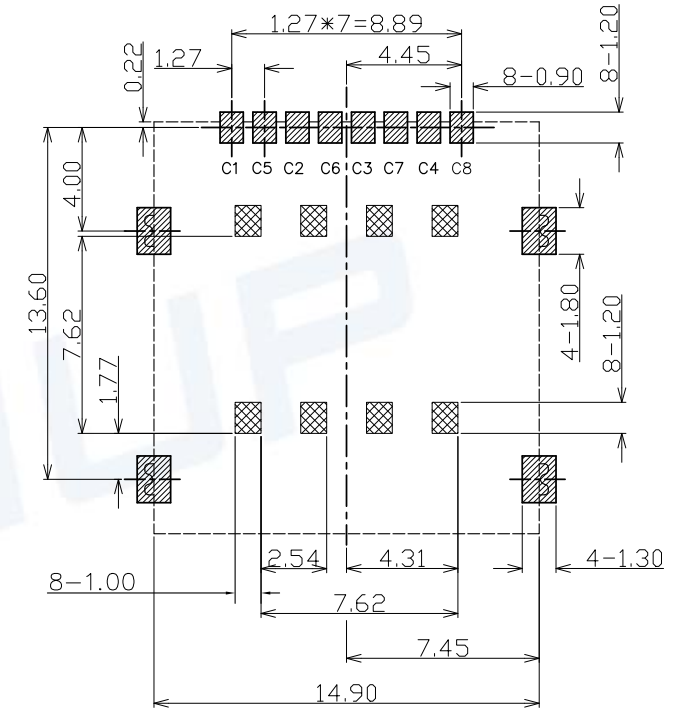
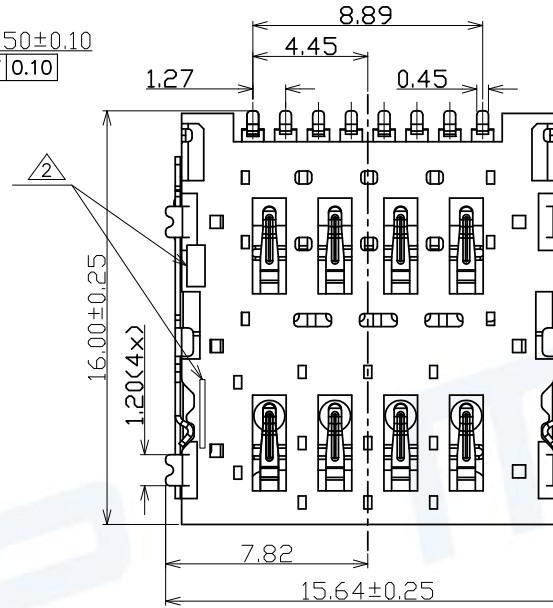
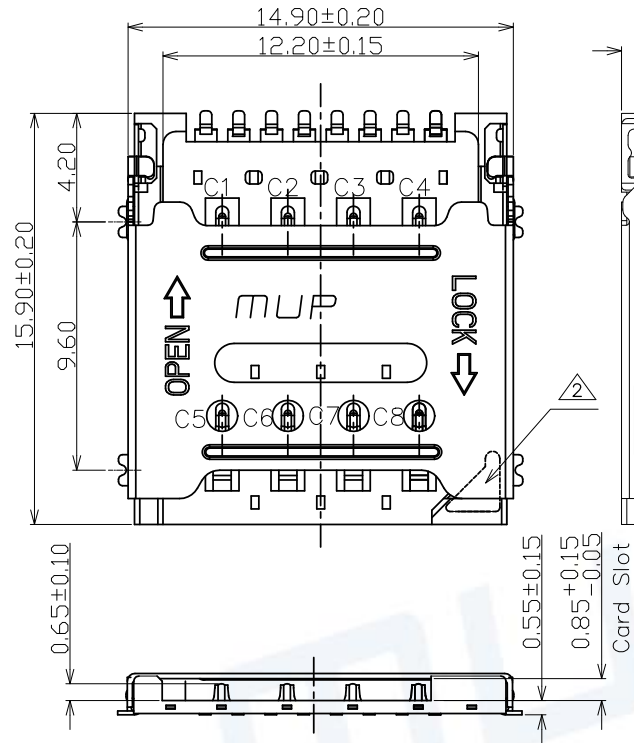


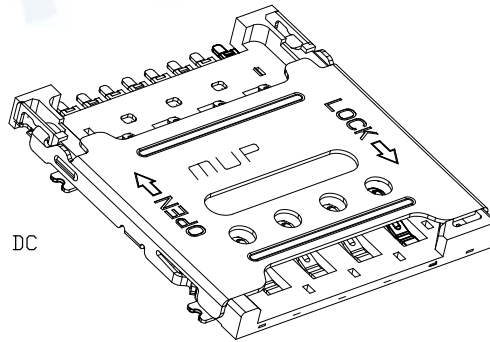
REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
△	NEW REVISION			Henry	2015/03/13
△	Plastic change			Henry	2022/08/11
△	Original Model C791-3			Henry	2023/10/19



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

- PAD AREA
 CONNECTOR OUTLINE
 NO PATTERN AND VIA HOLE IN THIS AREA

TECHNICAL CHARACTERISTICS
 1.General Characteristics
 Dimensions:15.90LX14.90WX1.50H mm
 Durability:5,000 cycles min.
 2.Electrical Characteristics
 Contact resistance:50mΩ typical,
 100mΩMax
 Insulation resistance:>1000M/500V DC
 3.Solderability
 Vaporphase:215°C, 30sec.Max
 IR reflow:260°C,5sec.Max
 Manual soldering:370°C,3sec.Max
 4.Environmental Characteristics
 Operating temperature:-40°C~+85°C
 Operating humidity:10%~+95%RH



Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:		MUP INDUSTRIAL CO.,LTD.	
X	±0.35	X*	±5°
X.X	±0.25	X.X*	±4°
X.XX	±0.15	X.XX*	±3°
X.XXX	±0.10	X.XXX*	±2°

NAME:		Micro-SIM Card Connector	
MODEL NO:		MUP-C7091-03	
TYPE :		H1.50mm 8 PIN(Long shell & New Body)	

PROJ.	UNIT	SCALE	DRAWN	Henry Mar.13.2015	DWG NO.:	DWG-C7091-03-01	
	mm	1:1	CHECKED	Henry Mar.13.2015	SHEET	1/1	REVISION
CUSTOMER DRAWING			APPROVAL	Simon Mar.13.2015	3		